

## TEST CONTACTING SOLUTION (PATENT PENDING)

The industry's leading precision thermal contacting solution for Mixed-Signal & automotive ICs from mid to high power test applications with precise Kelvin contactor for Leaded & Leadless devices.

Gamma featuring a customize cantilever contact pin & proprietary housing design with compression-mount contactor; delivers high performance in electrical & mechanical specifications from the laboratory to final test floor.

Do You Need	Gamma Offers		
Self cleaning	Scrubbing of $\approx 0.15$ mm (Kelvin)		
Tri-temperature testing (-60°C to +180°C) with ±2°C thermal control	Reliable temperature test with single piece pin construction & proprietary housing design		
Longer lifespan test solution	≥ 500K insertions (pin – on Matte Tin) ≥ 300K insertions (pin – on NiPd) ≥ 6M insertions (housing)		
Sustainable 1 <sup>st</sup> pass yield (FPY)	Longer MTBA, MTBR & MTBF		
Loadboard friendly	No mechanical movement & wearing on loadboard		
Lower cost of test (CoT)	Higher OEE		
Replaceable components	Modular design for ease of maintenance		



MSOP, TQFP, QFP, etc.

## GAMMA™ TEST CONTACTING SOLUTION

## **Design Features**

✓ ± 2°C thermal control

**Mechanical Specifications** 

Physical Pin Length (mm) Pin Uncompressed Height (mm)

Pin Compliance (mm)

Pin Wiping Length/pin (mm)

Gram Force Per Pin (g)

Number of Insertion - Housing

Number of Insertion – Pin (Matte Tin)

Number of Insertion - Pin (NiPd)

Operating temperature (°C)

Socket Material

Pin Material

- ✓ 4 Amp CCC
- ✓ Module assembly

- ✓ Tri-Temperature testing of -60°C up to +180°C
- ✓ Contact forces down to 25g∕pin

Gamma Outer

13.44

10~15

✓ Scrubbing Kelvin solution for ≥ 0.4mm pitch

Electrical Specifications $^{(1)}$	Single Contact (Non-Kelvin)	Dual Contact (Kelvin)	
Self Inductance (nH)	5.00	4.90	
Resistance (m $\Omega$ )	≤30	≤10	
Current Carrying Capacity - CCC (A) Duty Cycle 100%, 75%, 50%, 25%, 1% (300ms)	2.6, 3.1, 3.6, 6, 25.6		
Current Leakage (pA) @ 10V	≤ 1.0		

Gamma Inner

12.54

20~30

5.09 0.20

< 0.10

≥6M

≥ 500K

≥ 300K

- 60 to +180

TORLON® 5030 or equivalent

BeCu - Ni-Au



Without thermal refinement -Uneven heat distribution

	<u>.</u>		

Precision thermal socket design -Consistent DUT temperature



Contactor temperature simulation

(1) Results for 0.2mm thickness of pin



Note \* : The stated specifications are based on JF Microtechnology's Laboratory Test; the results may vary subjected to the test environment conditions. Information furnished by JF Microtechnology is believed to be accurate and reliable. However, no responsibility is assumed by JF Microtechnology for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of JF Microtechnology. Trademarks and registered trademarks are the property of their respective owners.

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Component breakdown of Gamma module assembly

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